

REVERSE COSTING® – STRUCTURE, PROCESS & COST REPORT





STMicroelectronics Proximity Sensor and Flood Illuminator

New time-of-flight and illumination device from the Apple iPhone 12.





Title: STMicroelectronics Proximity Sensor and Flood Illuminator

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Reference: SPR21576 This full reverse costing study has been conducted to provide insights into technology data, the manufacturing cost and selling price of the STMicroelectronics Proximity Sensor and Flood Illuminator in the Apple iPhone 12.

Located in the front above the main speaker, the proximity sensor and flood illuminator use optical Land Grid Array (LGA) packaging. The device is a custom version for Apple, coming after STMicroelectronics also released a custom proximity sensor for the iPhone X. While being 15% smaller than the previous version overall, the new version's flood illuminator is twice as large. The sensor is still based on FlightSense[™] technology.

The flood illuminator has a larger Vertical Cavity Surface Emitting Laser (VCSEL) die and VCSEL driver die. The diffuser is more sophisticated with a complexity close to a diffractive optical element.

To reduce the package size with larger components, STMicroelectronics has developed a 3D package with two stacked Printed Circuit Boards (PCBs). The 3D package manages the heat dissipation of the flood VCSEL thanks to a ceramic substrate, solder balls and PCB design.

This report analyzes the complete microsystem from the VCSEL illuminator of the proximity sensor manufactured by Trumpf to the VCSEL of the flood illuminator manufactured by Lumentum. It also analyzes the two integrated circuits with VCSEL driver from Texas Instruments and the Single Photon Avalanche Diode (SPAD) developed by STMicroelectronics. It includes analyses of the package, the diffuser and the filters with optical and Scanning Electron Microscopy pictures and Energy Dispersive X-ray analyses of the main semiconductor components. The report also includes a complete cost analysis and price estimation of the device based on a detailed description of the package, the Time-of-Flight detector, and the two VCSELs.

The report features also a complete technology comparison with the proximity sensor from the Apple iPhone X.

COMPLETE TEARDOWN WITH

- Explanation of device operation
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- Precise measurements
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AUTHORS



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Comparison iPhone X and iPhone 12 Proximity Sensor Manufacturing Process

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 - ✓ Die wafer and die cost
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Our analysis is performed with our costing tools LED CoSim+ and IC Price+.

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ABOUT SYSTEM PLUS CONSULTING

WHAT IS A REVERSE COSTING[®]?

Reverse Costing[®] is the process of disassembling a device (or a system) in order to identify its technology and calculate its manufacturing cost, using in-house models and tools.



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Peter OK Korea +82 10 4089 0233 peter.ok@yole.fr System Plus Consulting is specialized in the cost analysis of electronics from semiconductor devices to electronic systems.

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